Form PTO-1449 (modified)

Atty. Docket No.: 11762.0284.CNUS01 Serial No.:

09/923,058

List of Patents and Publications for Applicant's

NFORMATION DISCLOSURE STATEMENT

Applicants:

David S. Becker, et al.

(Use several sheets if necessary)

Filing Date: August 6, 2001

Group:

U.S. Patent Documents See Page 1

Foreign Patent Documents See Pages 1- 2

See Pages 2-3

U.S. Patent Documents

Exam. Init.		Ref. Des.	Document Number	Date	Name	Class	Sub Class	Filing Date of App.
Q()	39	A1	4,283,249	08/11/1981	Ephrath, L.M.	156	643	08/17/1979
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		A3	4,371,407	02/01/1983	Kurosawa, K.	148	187	10/28/1981
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		A9	5,200,358 🗸	04/06/1993	Bollinger, et al.	437	180	11/15/1991
\Box		A10	5,244,837 🗸	09/14/1993	Dennison, C.H.	437	195	03/19/1993
\perp		A11	5,290,726 🗸	03/01/1994	Kim, H.S.	437	52	02/18/1992
		A12	5,298,463 🗸	03/29/1994	Sandhu, et al.	437	192	04/16/1992
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EXAMINER: INITIAL IF REFERENCE ONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED. INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.

Form PTO-1449 (modified) Atty. Docket No.: Serial No.: 11762.0284.CNUS01 09/923,058 List of Patents and Publications for Applicant's **Applicants:** David S. Becker, et al. FORMATION DISCLOSURE STATEMENT Filing Date: Group: FEB 1 2 2003 (Use several sheets if necessary) August 6, 2001 **Patent Documents Foreign Patent Documents** Other Art See Page 1 See Pages 1-2 See Pages 2-3

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В3	JP02198634 V	08/07/1990	Japan	B01J	23/24	Abstract only
B4	JP03262503 V	11/22/1991	Japan	B01D	19/00	Abstract-unly
B5	JP04180222	06/26/1992	Japan	H01L	21/302	Abstract only
B6	JP04298032 V	10/21/1992	Japan	HOIL	21/302	Abstractorly
В7						
	B3 B4 B5 B6	Des. Number B3 JP02198634 ✓ B4 JP03262503 ✓ B5 JP04180222 ✓ B6 JP04298032 ✓	Des. Number B3 JP02198634 (08/07/1990) B4 JP03262503 (11/22/1991) B5 JP04180222 (06/26/1992) B6 JP04298032 (10/21/1992)	Des. Number Statisty B3 JP02198634 (08/07/1990) Japan B4 JP03262503 (11/22/1991) Japan B5 JP04180222 (06/26/1992) Japan B6 JP04298032 (10/21/1992) Japan	Des. Number Class B3 JP02198634 (08/07/1990) Japan B01J B4 JP03262503 (11/22/1991) Japan B01D B5 JP04180222 (06/26/1992) Japan H01L B6 JP04298032 (10/21/1992) Japan H01L	Des. Number Statistics B3 JP02198634 (08/07/1990) Japan B01J 23/24 B4 JP03262503 (11/22/1991) Japan B01D 19/00 B5 JP04180222 (06/26/1992) Japan H01L 21/302 B6 JP04298032 (10/21/1992) Japan H01L 21/302

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0	U	C2	Coburn, J.W.; Kay, E., "Some Chemical Aspects of the Fluorocarbon Plasma Etching of Silicon and Its Compounds", <i>IBM J. Res. Develop.</i> 1979, Vol. 23(1); 33-41.				
		C3	Toyoda, H.; Komiya, H.; Itakura, H., "Etching Characteristics of SiO ₂ in CHF ₃ Gas Plasma", J. Electronic Mat. 1980, Vol. 9(3); 569-584.				
		C4	Flamm, D.L.; Donnelly, V.M., "The Design of Plasma Etchants", Plasma Chemistry and Plasma Processing 1981, Vol. 1(4); 317-363.				
		C5	Kusters, K.H.; Sesselmann, W.; Melzner, H.; Friesel, B., "A Self Aligned Contact Process with Improved Surface Planarization", <i>Journal de Physique</i> 1988, Vol. 49, Colloque C4, Suppl. 9; C4503 – C4506.				
		C6	Chang, E.Y.; van Hove, J.M.; Pande, K.P., "A Selective Dry-Etch Technique for GaAs MESFET Gate Recessing", <i>IEEE Trans. Electron. Devices</i> 1988, Vol. 35(10); 1580-1584.				
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	George	youd read	DATE CONSIDERED:	5-03/

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One	С9	Simko, J.P.; Oehrlein, G.S., "Reactive Ion Etching of Silicon and Silicon Dioxide in CF ₄ Plasmas Containing H ₂ or C ₂ F ₄ Additives", J. Electrochem. Soc. 1991, Vol. 138 (9); 2748-2752.			
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	C11	Sakai, T.; Hayashi, H.; Abe, J.; Horioka, K.; Okano, H., "Examination of Selective Etching and Etching Damage with Mass-Selected Ion Beam", 1993 Dry Process Symposium; 193-198.			
	C12	Preliminary Invalidity Contentions regarding Parent Patent 5,286,344, filed in Sandisk Corp. v. Micron Tech., Inc., Civ. No. CV02-2627CW (N. D. Cal.).			
	C13	Preliminary Invalidity Contentions regarding Parent Patent 6,015,760, filed in Sandisk Corp. v. Micron Tech., Inc., Civ. No. CV02-2627CW (N. D. Cal.).			
TAG	C14	Preliminary Invalidity Contentions regarding Parent Patent 6,287,978, filed in Sandisk Corp. v. Micron Tech., Inc., Civ. No. CV02-2627CW (N. D. Cal.).			
	C15				

Examiner: George Goud real Date Considered: 5-03.

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